

AMENDMENT OF THE CLAIMS

Claims 1-11, 14-24, and 26-36 have been cancelled without disclaimer of the subject matter thereof. Claims 12, 13, and 25 were previously cancelled. New claims 37-61 have been added to the Application and find support in original claims 1-25. No new matter is believed added. The following listing of claims replaces all previous claims in this Application.

LISTING OF THE CLAIMS:

Claims 1-36 (Cancelled).

Claim 37 (New): A composite laminated substrate for integrated and minimized electronic circuits, comprising:

an inorganic substrate having at least one passive component embedded therein; and

an organic substrate which is laminated to one side of the inorganic substrate and which has circuits for electrical connections between outer input/output ports and the at least one passive component of the inorganic substrate.

Claim 38 (New): The composite laminated substrate according to claim 37, wherein the inorganic substrate is comprised of a material selected from the group consisting of ceramic, silicon and glass.

Claim 39 (New): The composite laminated substrate according to claim 38, wherein the material of the inorganic substrate is ceramic and wherein the at least one passive component is one of a thick film passive component made by a thick film process or a thin film passive component made by a thin film process.

Claim 40 (New): The composite laminated substrate according to claim 38, wherein the material of the inorganic substrate is silicon and wherein the at least one passive component is a semiconductor-fabricated passive component made by a semiconductor fabrication process

Claim 41 (New): The composite laminated substrate according to claim 37, wherein the at least one passive component is selected from the group consisting of a capacitor, an inductor, a resistor, and any mixture thereof.

Claim 42 (New): The composite laminated substrate according to claim 37, wherein the organic substrate is composed of a plurality of printed circuit board.

Claim 43 (New): The composite laminated substrate according to claim 42, wherein the plurality of printed circuit boards are stacked and have separately-fabricated circuitry respectively.

Claim 44 (New): The composite laminated substrate according to claim 43, wherein the organic substrate has an outer surface layer which is a built-up surface layer, which includes a circuit, and which is made by a build-up process

Claim 45 (New): The composite laminated substrate according to claim 37, wherein the organic substrate further comprises at least one passive component.

Claim 46 (New): The composite laminated substrate according to claim 45, wherein the at least one passive component of the organic substrate is selected from the group consisting of a capacitor, an inductor, a resistor, and any mixture thereof.

Claim 47 (New): The composite laminated substrate according to claim 37, wherein the

organic substrate is a built-up organic substrate provided on the inorganic substrate and made by a build-up process.

Claim 48 (New): The composite laminated substrate according to claim 37, further comprising a bonding layer which is provided between the inorganic substrate and the organic substrate, and which bonds together the inorganic substrate and the organic substrate.

Claim 49 (New): A composite laminated substrate for integrated and minimized electronic circuits, comprising:

an inorganic substrate having at least one passive component formed thereon or embedded therein; and

two organic substrates which are laminated to respective sides of the inorganic substrate and integrated therewith, and which have circuits for electrical connections between outer input/output ports and the at least one passive component of the inorganic substrate through the two organic substrates.

Claim 50 (New): The composite laminated substrate according to claim 49, wherein the inorganic substrate is comprised of a material selected from the group consisting of ceramic, silicon and glass.

Claim 51 (New): The composite laminated substrate according to claim 50, wherein the material of the inorganic substrate is ceramic and wherein the at least one passive component is one of a thick film passive component made by a thick film process or a thin film passive component made by a thin film process.

Claim 52 (New): The composite laminated substrate according to claim 50, wherein the material of the inorganic substrate is silicon and wherein the at least one passive

component is a semiconductor-fabricated passive component made by a semiconductor fabrication process.

Claim 53 (New): The composite laminated substrate according to claim 49, wherein the passive component is selected from the group consisting of a capacitor, an inductor and a resistor.

Claim 54 (New): The composite laminated substrate according to claim 49, wherein each of the two organic substrates is composed of a plurality of printed circuit boards.

Claim 55 (New): The composite laminated substrate according to claim 54, wherein each of the two organic substrates is composed of a plurality of printed circuit boards which are stacked respectively and wherein each printed circuit board of each respective plurality of printed circuit boards has separately-fabricated circuitry.

Claim 56 (New): The composite laminated substrate according to claim 55, wherein each of the two organic substrates has an outer surface layer which is a built-up surface layer, which includes a circuit, and which is made by a build-up process.

Claim 57 (New): The composite laminated substrate according to claim 49, wherein at least one of the two organic substrates further comprises at least one passive component.

Claim 58 (New): The composite laminated substrate according to claim 57, wherein the at least one passive component of the at least one of the two organic substrates is selected from the group consisting of a capacitor, an inductor, a resistor, and any mixture thereof.

Claim 59 (New): The composite laminated substrate according to claim 49, wherein at

least one of the two organic substrates is a built-up organic substrate provided on the inorganic substrate and made by a build-up process.

Claim 60 (New): The composite laminated substrate according to claim 49, further comprising a covering layer which is provided on the inorganic substrate and covers the inorganic substrate, which integrates the inorganic substrate with one of the two organic substrates, and which comprises circuits for providing electrical connections between the at least one passive component of the inorganic substrate and said one of the two organic substrates,

wherein the inorganic substrate is fully embedded in said one of the two organic substrates.

Claim 61 (New): The composite laminated substrate according to claim 49, further comprising a bonding layer which is provided between the inorganic substrate and at least one of the two organic substrates, and which bonds together the inorganic substrate and said at least one of the two organic substrates.